

ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

Title of Invention

IC PACKAGE HAVING GROUND IC CHIP AND METHOD OF
MANUFACTURING SAME

Application Number :

Confirmation Number:

First Named Applicant: PEI-HAW TSAO

Attorney Docket Number: TSMC2003-1622

Art Unit:

Examiner:

Search string: (6552267 or 6607942 or 6656827 or 20030211720 or 20030219987 or
20030045028).pn

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
	1	6552267	2003-04-22	Tsao et al.			
	2	6607942	2003-08-19	Tsao et al.			
	3	6656827	2003-12-02	Tsao et al.			

US Published Applications

Note: Applicant is not required to submit a paper copy of cited US Published Applications

init	Cite.No.	Pub. No.	Date	Applicant	Kind	Class	Subclass
	1	20030211720	2003-11-13	Huang et al.			
	2	20030219987	2003-11-27	Wang et al.			
	3	20030045028	2003-03-06	Tsao et al.			

Signature

Examiner Name	Date